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TLE7274-2

5-V Low Dropout Voltage Regulator

TLE7274-2E TLE7274-2D TLE7274-2G

Data Sheet

Rev. 1.01, 2011-11-30

Automotive Power



5-V Low Dropout Voltage Regulator

TLE7274-2





1 Overview

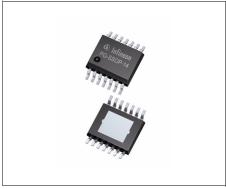
Features

- Ultra Low Current Consumption 20 μA
- Output Voltage 5 V ±2%
- Output Current up to 300 mA
- · Very Low Dropout Voltage
- Output Current Limitation
- · Overtemperature Shutdown
- Wide Temperature Range From -40 °C up to 150 °C
- Green Product (RoHS compliant)
- AEC Qualified



The TLE7274-2 is a monolithic integrated low dropout voltage regulator for load currents up to 300 mA. An input voltage up to 42 V is regulated to $V_{\rm Q,nom}$ = 5.0 V with a precision of $\pm 2\%$. The sophisticated design allows to achieve stable operation even with ceramic output capacitors down to 470 nF. The device is designed for the harsh environment of automotive applications. Therefore it is protected against overload, short circuit and overtemperature conditions by the implemented output current limitation and the overtemperature shutdown circuit. The TLE7274-2 can be also used in all other applications requiring a stabilized 5 V voltage.

Due to its ultra low quiescent current of typically 20 μ A the TLE7274-2 is dedicated for use in applications permanently connected to $V_{\rm BAT}$. An integrated output sink current circuitry keeps the voltage at the Output pin Q below 5.5 V even in case of occuring reverse currents. Thus connected devices are protected from overvoltage damage. For applications requiring extremely low noise levels the Infineon voltage regulator family TLE 42XX and TLE 44XX is more suited than the TLE7274-2. A mV-range output noise on the TLE7274-2 caused by the charge pump operation is unavoidable due to the ultra low quiescent current concept.



PG-SSOP-14 Exposed Pad



PG-TO252-3



PG-TO263-3

Туре	Package	Marking
TLE7274-2E	PG-SSOP-14 Exposed Pad	7274-2E
TLE7274-2D	PG-TO252-3	7274-2D
TLE7274-2G	PG-TO263-3	7274-2G

Data Sheet 2 Rev. 1.01, 2011-11-30



Block Diagram

2 Block Diagram

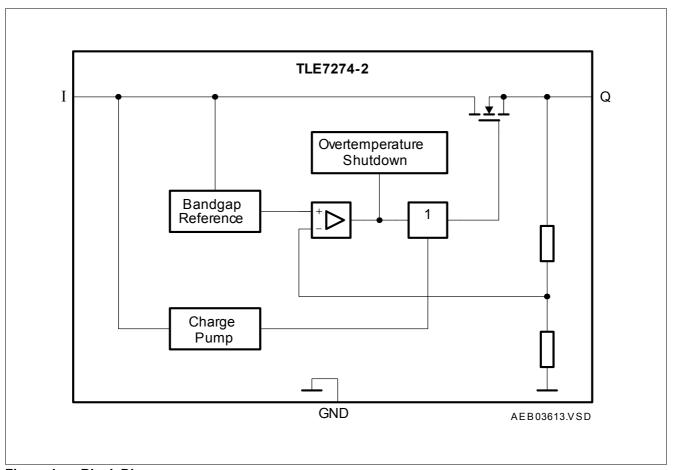


Figure 1 Block Diagram



Pin Configuration

3 Pin Configuration

3.1 Pin Assignment PG-SSOP-14 Exposed Pad

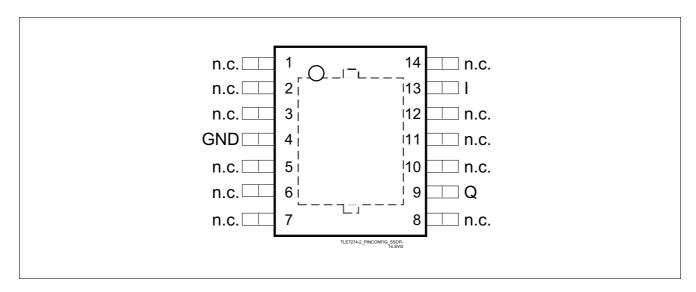


Figure 2 Pin Configuration (top view)

3.2 Pin Definitions and Functions PG-SSOP-14 Exposed Pad

Pin No.	Symbol	Function
1,2,3,5,6,7	n.c.	non connected
		can be open or connected to GND
4	GND	Ground
8,10,11,12,14	n.c.	non connected
		can be open or connected to GND
9	Q	Output
		block to ground with a capacitor close to the IC terminals, respecting the values given
		for its capacitance and ESR in "Functional Range" on Page 6
13	I	Input
		block to ground directly at the IC with a ceramic capacitor
Pad	_	Exposed Pad
		connect to GND and heatsink area



Pin Configuration

3.3 Pin Assignment PG-TO252-3, PG-TO263-3

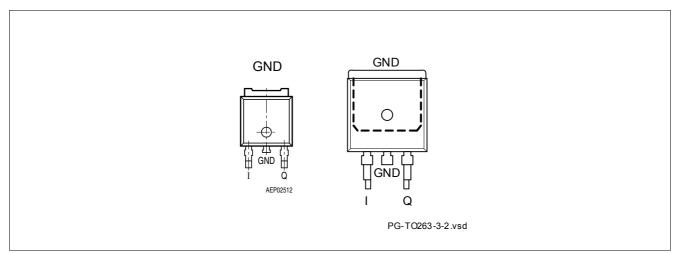


Figure 3 Pin Configuration (top view)

3.4 Pin Definitions and Functions PG-TO252-3, PG-TO263-3

Pin No.	Symbol	Function
1	1	Input block to ground directly at the IC with a ceramic capacitor
2	GND	Ground internally connected to heat slug
3	Q	Output block to ground with a capacitor close to the IC terminals, respecting the values given for its capacitance and ESR in "Functional Range" on Page 6
Heat Slug	_	Heat Slug internally connected to GND; connect to GND and heatsink area



General Product Characteristics

4 General Product Characteristics

4.1 Absolute Maximum Ratings

Absolute Maximum Ratings1)

 T_i = -40 °C to 150 °C; all voltages with respect to ground, (unless otherwise specified)

Pos.	Parameter	Symbol	Lim	nit Values	Unit	Test Condition
			Min.	Max.		
Input I	,	1	1	1	1	1
4.1.1	Voltage	V_{l}	-0.3	45	V	_
Output	Q			*		-
4.1.2	Voltage	V_{Q}	-0.3	6	V	_
4.1.3	Voltage	V_{Q}	-0.3	6.2	V	$t < 10 \text{ s}^{2)}$
Tempe	rature			*		-
4.1.4	Junction temperature	T_{j}	-40	150	°C	_
4.1.5	Storage temperature	T_{stg}	-50	150	°C	_
ESD St	sceptibility	-	- 1		1	'
4.1.6	Human Body Model (HBM) ³⁾	Voltage	-	3	kV	_
4.1.7	Charged Device Model (CDM) ⁴⁾	Voltage	-	1.5	kV	_

¹⁾ not subject to production test, specified by design

Note: Stresses above the ones listed here may cause permanent damage to the device. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Note: Integrated protection functions are designed to prevent IC destruction under fault conditions described in the data sheet. Fault conditions are considered as "outside" normal operating range. Protection functions are not designed for continuous repetitive operation.

4.2 Functional Range

Pos.	Parameter	Symbol	Limit Values		Unit	Remarks	
			Min.	Max.			
4.2.1	Input voltage	V_1	5.5	42	V	-	
4.2.2	Output Capacitor's	C_{Q}	470	_	nF	1)	
4.2.3	Requirements	$ESR(C_{Q})$	_	10	Ω	2)	
4.2.4	Junction temperature	$T_{\rm j}$	-40	150	°C	_	

¹⁾ the minimum output capacitance requirement is applicable for a worst case capacitance tolerance of 30%

Note: Within the functional or operating range, the IC operates as described in the circuit description. The electrical characteristics are specified within the conditions given in the Electrical Characteristics table.

²⁾ exposure to these absolute maximum ratings for extended periods (t > 10 s) may affect device reliability

³⁾ ESD susceptibility Human Body Model "HBM" according to AEC-Q100-002 - JESD22-A114

⁴⁾ ESD susceptibility Charged Device Model "CDM" according to ESDA STM5.3.1

²⁾ relevant ESR value at f = 10 kHz



General Product Characteristics

4.3 Thermal Resistance

Note: This thermal data was generated in accordance with JEDEC JESD51 standards. For more information, go to www.jedec.org.

Pos.	Parameter	Symbol		Limit Val	ues	Unit	Conditions
			Min.	Тур.	Max.		
TLE72	74-2E (PG-SSOP-14 Exposed	Pad)			1		
4.3.1	Junction to Case ¹⁾	R_{thJC}	_	14	_	K/W	measured to
							exposed pad
4.3.2	Junction to Ambient ¹⁾	R_{thJA}	_	47	_	K/W	2)
4.3.3		R_{thJA}	_	141	_	K/W	footprint only ³⁾
4.3.4		R_{thJA}	_	66	_	K/W	300 mm² heatsink area ³⁾
4.3.5		R_{thJA}	_	56	-	K/W	600 mm² heatsink area ³⁾
TLE72	74-2D (PG-TO252-3)	1	"			<u> </u>	
4.3.1	Junction to Case ¹⁾	R_{thJC}	_	6	_	K/W	measured to tab
4.3.2	Junction to Ambient ¹⁾	R_{thJA}	_	32	_	K/W	2)
4.3.3		R_{thJA}	_	115	_	K/W	footprint only ³⁾
4.3.4		R_{thJA}	_	62	_	K/W	300 mm² heatsink area ³⁾
4.3.5		R_{thJA}	_	47	-	K/W	600 mm² heatsink area ³⁾
TLE72	74-2G (PG-TO263-3)				1		
4.3.1	Junction to Case ¹⁾	R_{thJC}	_	6	-	K/W	measured to exposed pad
4.3.2	Junction to Ambient ¹⁾	R_{thJA}	_	27	_	K/W	2)
4.3.3		R_{thJA}	_	75	_	K/W	footprint only ³⁾
4.3.4		R_{thJA}	_	47	-	K/W	300 mm² heatsink area ³⁾
4.3.5		R_{thJA}	_	38	-	K/W	600 mm² heatsink area ³⁾

¹⁾ Not subject to production test, specified by design.

²⁾ Specified R_{thJA} value is according to Jedec JESD51-2,-5,-7 at natural convection on FR4 2s2p board; The Product (Chip+Package) was simulated on a 76.2 x 114.3 x 1.5 mm³ board with 2 inner copper layers (2 x 70μm Cu, 2 x 35μm Cu). Where applicable a thermal via array under the exposed pad contacted the first inner copper layer.

³⁾ Specified R_{thJA} value is according to Jedec JESD 51-3 at natural convection on FR4 1s0p board; The Product (Chip+Package) was simulated on a 76.2 \times 114.3 \times 1.5 mm³ board with 1 copper layer (1 x 70 μ m Cu).



5 Electrical Characteristics

5.1 Electrical Characteristics Voltage Regulator

Electrical Characteristics

 V_i =13.5 V; T_i = -40 °C to 150 °C; all voltages with respect to ground (unless otherwise specified)

Pos.	Parameter	Symbol	Limit Values			Unit	Measuring Condition	
			Min.	Тур.	Max.			
Output	Q				<u>'</u>			
5.1.1	Output Voltage	V_{Q}	4.9	5.0	5.1	V	0.1 mA < I _Q <300 mA 6 V < V _I < 16 V	
5.1.2	Output Voltage	V_{Q}	4.9	5.0	5.1	V	0.1 mA < I _Q <100 mA 6 V < V _I < 40 V	
5.1.3	Dropout Voltage	V_{dr}	_	250	500	mV	$I_{\rm Q}$ = 200 mA $V_{\rm dr} = V_{\rm I} - V_{\rm Q}^{-1}$	
5.1.4	Load Regulation	$\Delta V_{Q,lo}$	- 40	15	40	mV	$I_{\rm Q}$ = 5 mA to 250 mA	
5.1.5	Line Regulation	$\Delta V_{Q,li}$	- 20	5	20	mV	$V_{\rm I}$ = 10 V to 32 V $I_{\rm Q}$ = 5 mA	
5.1.6	Output Current Limitation	I_{Q}	301	_	_	mA	1)	
5.1.7	Output Current Limitation	I_{Q}	_	_	800	mA	$V_{Q} = 0V$	
5.1.8	Power Supply Ripple Rejection ²⁾	PSRR	_	60	_	dB	$f_{\rm r}$ = 100 Hz; $V_{\rm r}$ = 0.5 Vpp	
5.1.9	Temperature Output Voltage Drift	$\frac{dV_{Q}}{dT}$	_	0.5	-	mV/K	-	
Curren	t Consumption	1					1	
5.1.10	Quiescent Current $I_{q} = I_{l} - I_{Q}$	I_{q}	_	20	30	μΑ	$I_{\rm Q}$ = 0.1 mA $T_{\rm j}$ = 25 °C	
5.1.11	Quiescent Current $I_{q} = I_{l} - I_{Q}$	I_{q}	_	_	40	μΑ	$I_{\rm Q}$ = 0.1 mA $T_{\rm i} \le 80~{\rm ^{\circ}C}$	

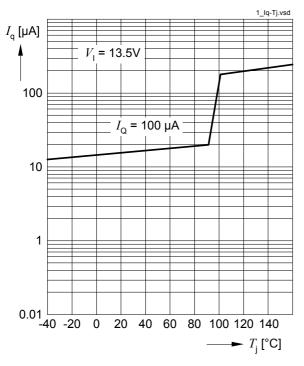
¹⁾ Measured when the output voltage $V_{\rm Q}$ has dropped 100 mV from the nominal value obtained at $V_{\rm I}$ = 13.5 V.

²⁾ not subject to production test, specified by design

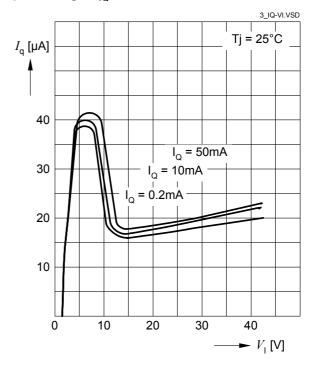


5.2 Typical Performance Characteristics Voltage Regulator

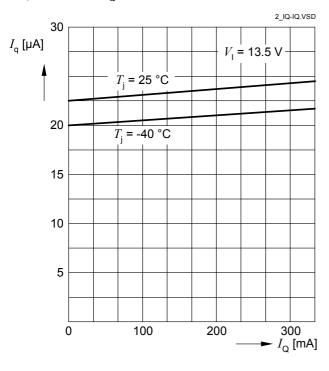
Current Consumption $I_{\rm q}$ versus Junction Temperature $T_{\rm J}$



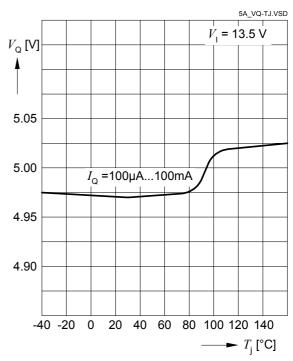
Current Consumption $I_{\rm q}$ versus Input Voltage $V_{\rm IQ}$



Current Consumption $I_{\rm q}$ versus Output Current $I_{\rm O}$

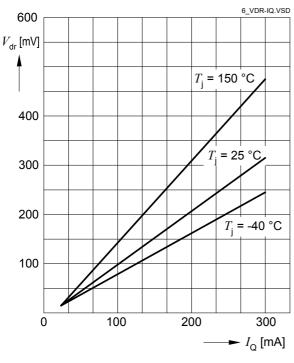


Output Voltage $V_{\rm Q}$ versus Junction Temperature $T_{\rm J}$

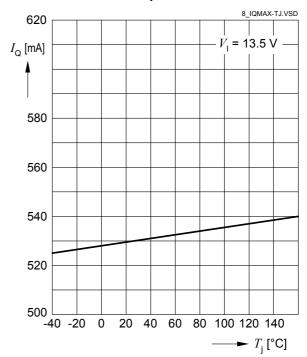




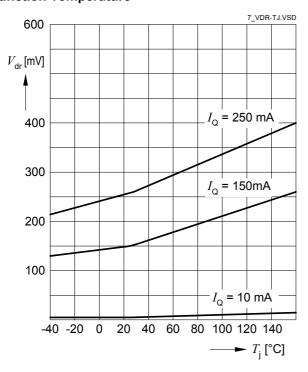
Dropout Voltage V_{dr} versus Output Current I_{Q}



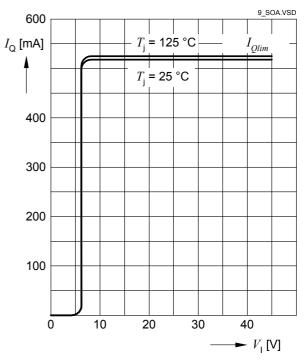
Maximum Output Current $I_{\rm Q}$ versus Junction Temperature $T_{\rm i}$



$\begin{array}{c} {\rm Dropout\ Voltage\ } V_{\rm dr}\ {\rm versus} \\ {\rm Junction\ Temperature} \end{array}$

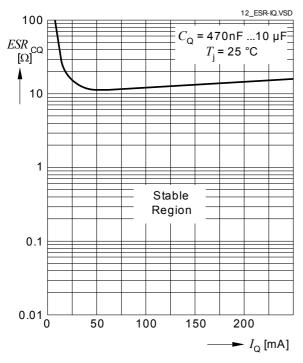


Maximum Output Current I_{Q} versus Input Voltage V_{I}

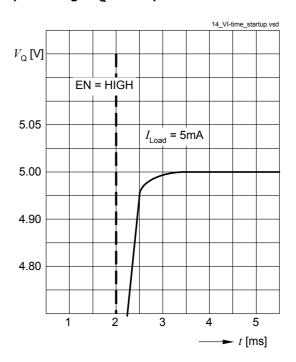




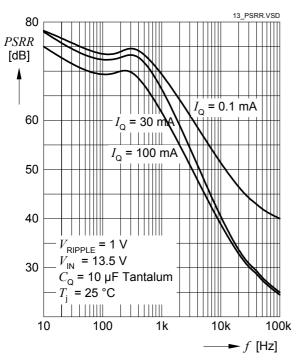
Region of Stability



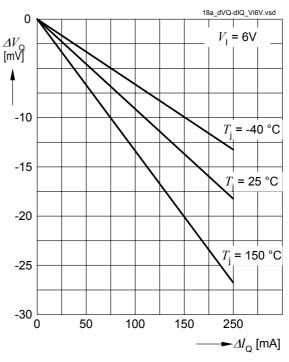
Output Voltage V_{Q} Start-up behavior



Power Supply Ripple Rejection PSRR versus Frequency f

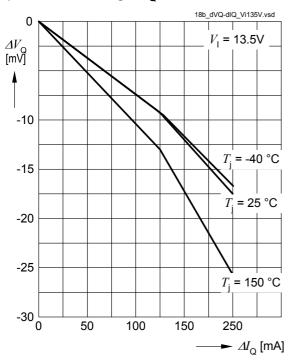


Load Regulation $\Delta V_{\rm Q}$ versus Output Current Change $\Delta I_{\rm Q}$

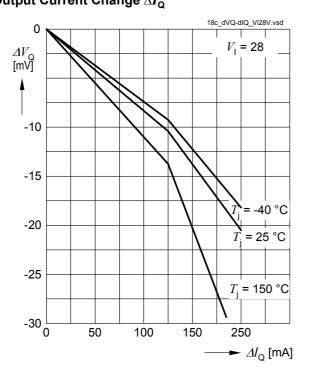




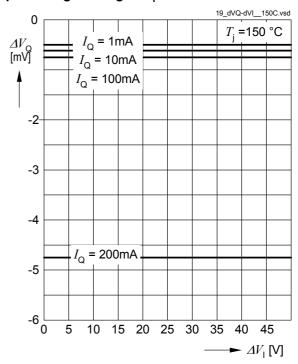
Load Regulation $\Delta V_{\rm Q}$ versus Output Current Change $dI_{\rm Q}$



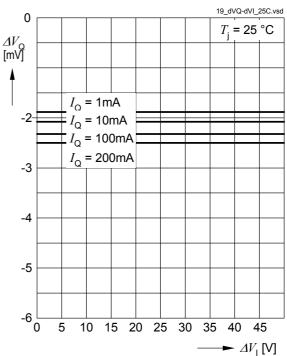
Load Regulation $\Delta V_{\rm Q}$ versus Output Current Change $\Delta I_{\rm Q}$



Line Regulation ΔV_{Q} versus Input Voltage Changed V_{I}

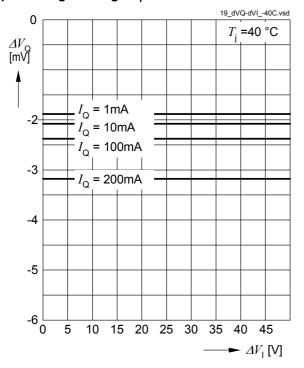


Line Regulation ΔV_{Q} versus Input Voltage Changed V_{I}

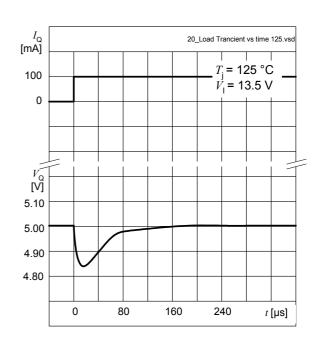




Line Regulation $\Delta V_{\rm Q}$ versus Input Voltage Change $V_{\rm I}$

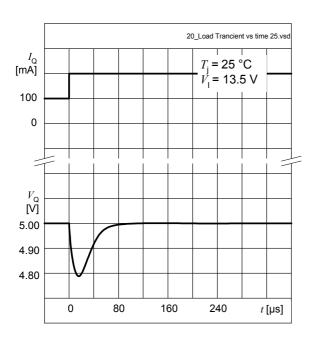


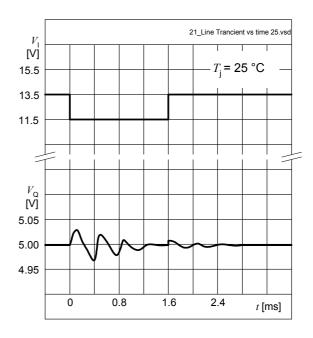
Load Transient Response Peak Voltage ΔV_{Q}



Load Transient Response Peak Voltage $\Delta V_{
m Q}$

Line Transient Response Peak Voltage ΔV_{Q}

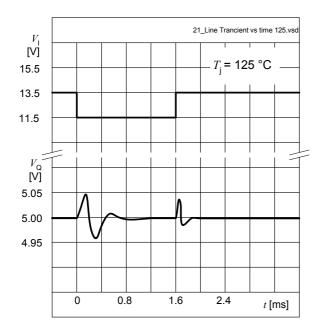






Line Transient Response Peak Voltage ΔV_{Q}

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Package Outlines

6 Package Outlines

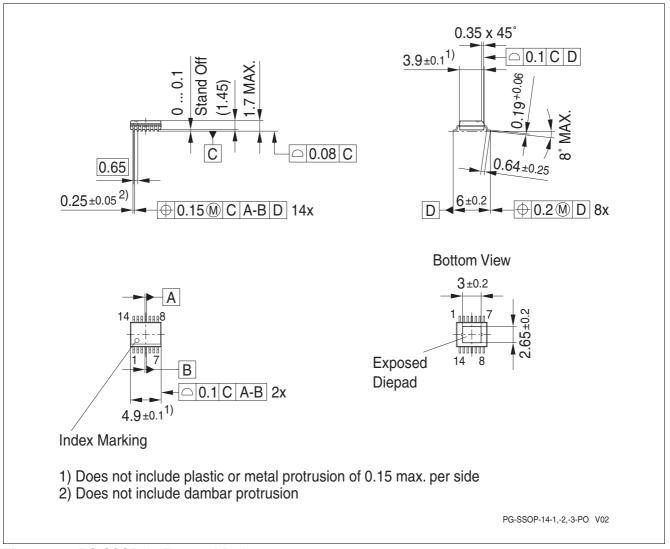


Figure 4 PG-SSOP-14 Exposed Pad



Package Outlines

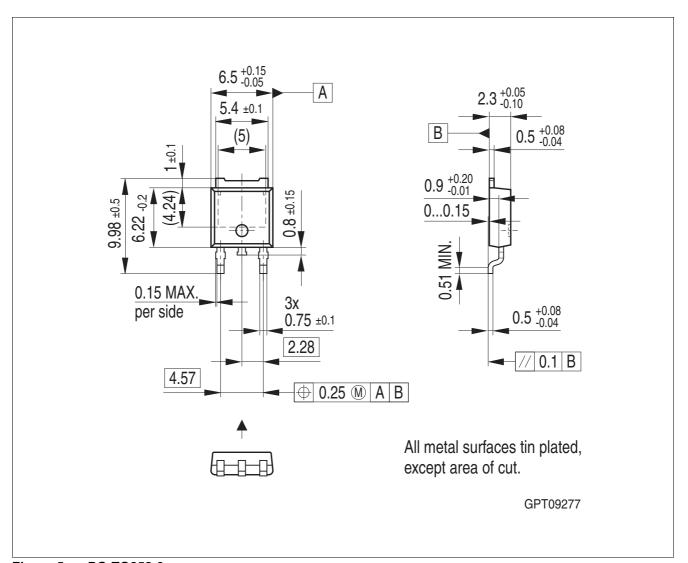


Figure 5 PG-TO252-3



Package Outlines

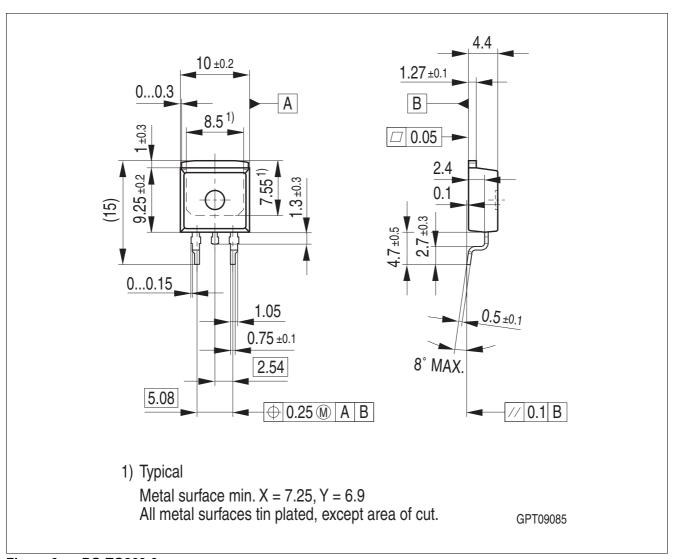


Figure 6 PG-TO263-3

Green Product (RoHS compliant)

To meet the world-wide customer requirements for environmentally friendly products and to be compliant with government regulations the device is available as a green product. Green products are RoHS-Compliant (i.e Pb-free finish on leads and suitable for Pb-free soldering according to IPC/JEDEC J-STD-020).



Revision History

7 Revision History

Revision	Date	Changes		
1.01	2011-11-30	updated version data sheet: (no change in function or design of device)		
		Package TO263-3 corrected to TO263-3-2.		
		in "Overview" on Page 2 Package Drawing corrected.		
		in "Pin Assignment PG-TO252-3, PG-TO263-3" on Page 5 Pin Assignment for		
		TO263-3 corrected and Headlines added.		
		in Figure 6 "PG-TO263-3" on Page 18 Package Outlines corrected		
		in "Electrical Characteristics Voltage Regulator" on Page 8, former Item		
		5.1.12 "Current Consumption, Regulator Disabled" removed, in Condition of		
		Item 5.1.10 and Item 5.1.11 " $V_{\rm EN}$ = 5 V" removed: Non relevant information as		
		TLE7270-2 does not implement Enable Feature		
1.0	2009-06-01	1 initial version data sheet		

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